



Material Content Data Sheet



Sales Product Name				ESD103-B1-02ELS E6327		Issued		20. July 2018	
MA#				MA001248188					
Package				PG-TSSLP-2-4		Weight*		0.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.17		1667		
	noble metal	gold	7440-57-5	0.001	0.65		6459		
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47874	56000	
leadframe	non noble metal	nickel	7440-02-0	0.108	51.63	51.63	516380	516380	
wire	noble metal	gold	7440-57-5	0.003	1.32	1.32	13195	13195	
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1887		
	plastics	epoxy resin	-	0.011	5.47		54686		
	inorganic material	silicondioxide	60676-86-0	0.067	32.06	37.72	320584	377157	
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17619	17619	
plating	noble metal	gold	7440-57-5	0.004	1.96	1.96	19649	19649	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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